

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): An electronic component wherein a lead frame is attached to an element with an electrically conductive adhesive,

the electronic component being characterized in that the lead frame has an adhesive filling portion formed at a part thereof having a lower surface opposed to the element, the adhesive filling portion being one of a hole, cavity, cutout and groove formed in the lead frame, the filling portion having an inside thereof filled with the conductive adhesive.

Claim 2 (Cancelled).

Claim 3 (Currently Amended): An electronic component wherein a lead frame is attached to an element with an electrically conductive adhesive,

the electronic component being characterized in that the lead frame has an adhesive filling portion formed at a part thereof having a lower surface opposed to the element, the filling portion having an inside thereof filled with the conductive adhesive, ~~according to claim 2~~ wherein the lead frame is provided with a plurality of grooves intersecting one another and divided into a plurality of frame segments by the grooves.

Claim 4 (Currently Amended): An electronic component according to claim ~~1~~ 3 which is a solid electrolytic capacitor and wherein the element is a capacitor element.

Claim 5 (New): An electronic component according to claim 1 which is a solid electrolytic capacitor and wherein the element is a capacitor element.

Claim 6 (New): An electronic component according to claim 5 wherein the capacitor element is covered with a synthetic resin housing.

Claim 7 (New): An electronic component according to claim 4 wherein the capacitor element is covered with a synthetic resin housing.